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NDT3055L Rev.A1



NDT3055L N-Channel Logic Level Enhancement Mode Field Effect Transistor

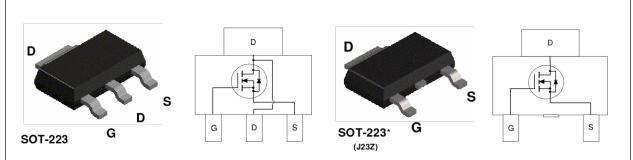
General Description

These logic level N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process is especially tailored to minimize on-state resistance and provide superior switching performance, and withstand high energy pulse in the avalanche and commutation modes. These devices are particularly suited for low voltage applications such as DC motor control and DC/DC conversion where fast switching, low in-line power loss, and resistance to transients are needed.

Features

- Low drive requirements allowing operation directly from logic drivers. V_{GS(TH)} < 2V.
- High density cell design for extremely low R_{DS(ON)}.
- High power and current handling capability in a widely used surface mount package.





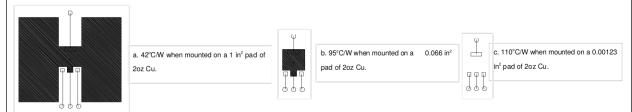
Absolute Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter		NDT3055L	Units	
V _{DSS}	Drain-Source Voltage		60	V	
V _{GSS}	Gate-Source Voltage - Continuous		±20	V	
I _D	Maximum Drain Current - Continuous (Note 1a) - Pulsed		4	A	
			25		
P _D	Maximum Power Dissipation	(Note 1a)	3	W	
		(Note 1b)	1.3		
		(Note 1c)	1.1		
$\Gamma_{\rm J}, T_{ m STG}$	Operating and Storage Temperature Range		-65 to 150	°C	
THERMA	L CHARACTERISTICS	•		•	
R _{ejia}	Thermal Resistance, Junction-to-Ambie	ent (Note 1a)	42	°C/W	
R _{euc}	Thermal Resistance, Junction-to-Case	(Note 1)	12	°C/W	

Symbol	Parameter	Conditions		Min	Тур	Max	Units
OFF CHAF	RACTERISTICS	·					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$		60			V
Δ BV _{DSS} / Δ T _J	Breakdown Voltage Temp. Coefficient	I _D = 250 μA, Referenced to 25 °C			55		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 60 V, V _{GS} = 0 V				1	μА
		T _J =125°C	T _J =125°C			50	μА
GSSF	Gate - Body Leakage, Forward	V _{GS} = 20 V, V _{DS} = 0 V				100	nA
GSSR	Gate - Body Leakage, Reverse	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$				-100	nA
ON CHARA	ACTERISTICS (Note 2)						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		1	1.6	2	V
$\Delta V_{GS(th)}/\Delta T_{J}$	Gate Threshold Voltage Temp. Coefficient	I _D = 250 μA, Referenced to 25 °C			-4		mV /°C
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 4 A			0.07	0.1	Ω
		[-	T _J =125°C		0.125	0.18	
		$V_{GS} = 4.5 \text{ V}, I_D = 3.7 \text{ A}$			0.103	0.12	
I _{D(ON)}	On-State Drain Current	$V_{GS} = 5$, $V_{DS} = 10 \text{ V}$		10			Α
g _{FS}	Forward Transconductance	$V_{DS} = 5 \text{ V}, I_{D} = 4 \text{ A}$			7		S
DYNAMIC (CHARACTERISTICS						
C _{iss}	Input Capacitance	$V_{DS} = 25, V_{GS} = 0 \text{ V},$ f = 1.0 MHz			345		pF
C _{oss}	Output Capacitance				110		pF
C _{rss}	Reverse Transfer Capacitance				30		pF
SWITCHING	G CHARACTERISTICS (Note 2)						
t _{D(on)}	Turn - On Delay Time	$V_{DD} = 25$, $I_{D} = 1$ A, $V_{GS} = 10$ V, $R_{GEN} = 6$ Ω			5	20	ns
t r	Turn - On Rise Time				7.5	20	ns
D(off)	Turn - Off Delay Time				20	50	ns
f	Tum - Off Fall Time				7	20	ns
Q _g	Total Gate Charge	$V_{DS} = 40 \text{ V}, \ I_{D} = 4 \text{ A}, \ V_{GS} = 10 \text{ V}$			13	20	nC
Q_{gs}	Gate-Source Charge				1.7		nC
Q_{gd}	Gate-Drain Charge				3.2		nC
DRAIN-SO	JRCE DIODE CHARACTERISTICS AND MAX	IMUM RATINGS					
s	Maximum Continuous Drain-Source Diode Forward Current					2.5	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 2.5 \text{ A} \text{ (Note 2)}$			0.8	1.2	V

Notes

the drain pins. $\boldsymbol{R}_{\text{BJC}}$ is

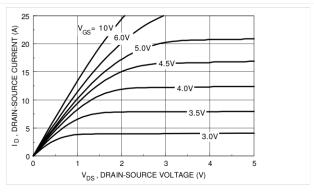


Scale 1:1 on letter size paper

2. Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2.0%

R_{BiA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of guaranteed by design while R_{BCA} is determined by the user's board design.

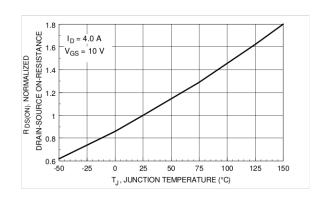
Typical Electrical Characteristics



1.8 V GSS = 4.0V STAN CURRENT (A) 1.8 V GSS = 4.0V STAN CURRENT (A) 1.0 DROWN CURRENT (A) 1.0 DROWN CURRENT (A) 1.0 DROWN CURRENT (A) 2.0 DROWN CURRENT (A

Figure 1. On-Region Characteristics.

Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.



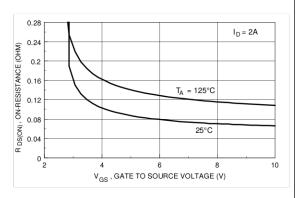
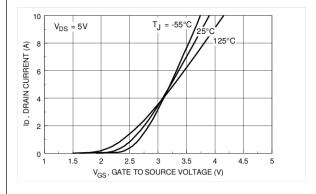


Figure 3. On-Resistance Variation with Temperature.

Figure 4. On-Resistance Variation with Gate-to- Source Voltage.



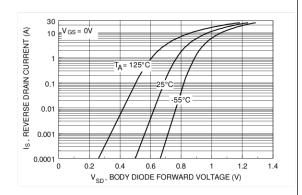
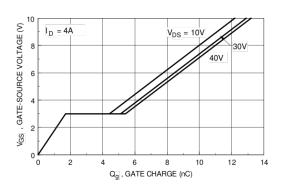


Figure 5. Transfer Characteristics.

Figure 6. Body Diode Forward Voltage Variation with Current and Temperature.

Typical Electrical Characteristics (continued)



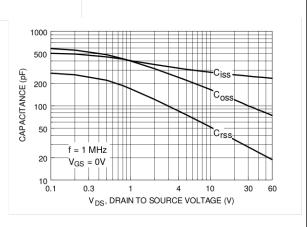
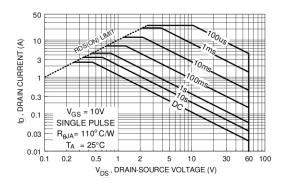


Figure 7. Gate Charge Characteristics.





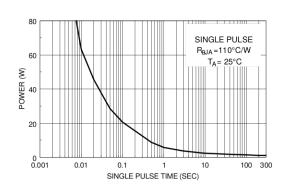


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

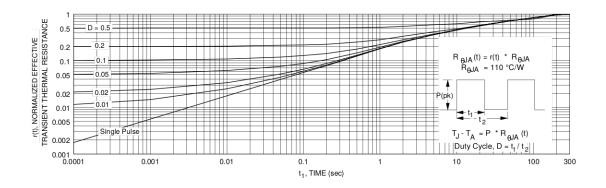
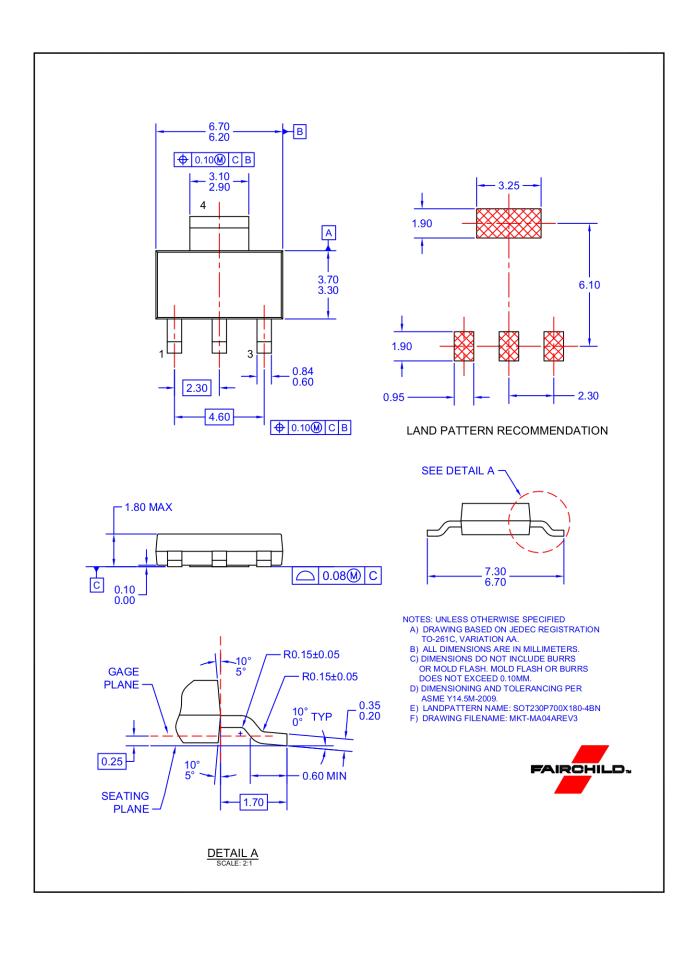


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in note 1c.

Transient thermal response will change depending on the circuit board design.



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